

1                    **DECLARATION OF JOINT INVENTORS FOR PATENT APPLICATION**

2                    As the below named inventor, I hereby declare that:

3                    My residence, post office address and citizenship are as stated  
4                    below next to my name.

5                    I believe I am the original, first and joint inventor of the subject  
6                    matter which is claimed and for which a patent is sought on the  
7                    invention entitled: Methods of Bonding Solder Balls to Bond Pads on  
8                    a Substrate, and Bonding Frames, the specification of which is attached  
9                    hereto.

10                  I hereby state that I have reviewed and understand the contents  
11                  of the above-identified specification, including the claims.

12                  I acknowledge the duty to disclose information known to me to  
13                  be material to patentability as defined in Title 37, Code of Federal  
14                  Regulations §1.56.

15                  **PRIOR FOREIGN APPLICATIONS:**

16                  I hereby state that no applications for foreign patents or inventor's  
17                  certificates have been filed prior to the date of execution of this  
18                  declaration.

19                  I hereby declare that all statements made herein of my own  
20                  knowledge are true and that all statements made on information and  
21                  belief are believed to be true; and further that these statements were  
22                  made with the knowledge that willful false statements and the like so  
23                  made are punishable by fine or imprisonment, or both, under  
24                  Section 1001 of Title 18 of the United States Code and that such willful

1      false statement may jeopardize the validity of the application or any  
2      patent issued therefrom.

3      \* \* \* \* \*

4      Full name of inventor:      **Warren M. Farnworth**

5      Inventor's Signature: \_\_\_\_\_

6      Date: \_\_\_\_\_

7      Residence:      **Nampa, Idaho**

8      Citizenship:      **U.S.A.**

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10                                 **Nampa, ID 83686**

11      \* \* \* \* \*

12      Full name of inventor:      **Alan G. Wood**

13      Inventor's Signature: \_\_\_\_\_

14      Date: \_\_\_\_\_

15      Residence:      **Boise, Idaho**

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